

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A thin forming apparatus (~~100~~) including a substrate support (~~10~~) for mounting a substrate (~~P~~) on which a thin film is to be formed, and a chamber (~~30~~) which encloses the substrate support (~~10~~) and has proper operation conditions, comprising:

adsorption means (~~S~~) attached to surfaces of components within the thin film forming apparatus except the substrate (~~P~~).

2. (Currently Amended) The apparatus as claimed in claim 1, wherein each of the adsorption means (~~S~~) is constructed by applying a solder metal material (~~H~~) on a surface of a metal base material (~~B~~).

3. (Currently Amended) The apparatus as claimed in claim 1, wherein each of the adsorption means (~~S~~) is constructed by applying solder metal material (~~H~~) on a surface of a synthetic resin base material (~~B~~).

4. (Currently Amended) The apparatus as claimed in claim 2 ~~or 3~~, wherein a plurality of grooves are formed on the surface of the based material (~~B~~).

5. (Currently Amended) The apparatus as claimed in claim 2 ~~or 3~~, wherein a plurality of protrusions are formed on the surface of the base material (~~B~~).

6. (Currently Amended) The apparatus as claimed in claim 2 ~~or 3~~, wherein the base material (~~B~~) is in the form of a net.

7. (New) The apparatus as claimed in claim 3, wherein a plurality of grooves are formed on the surface of the based material.

8. (New) The apparatus as claimed in claim 3, wherein a plurality of protrusions are formed on the surface of the base material.

9. (New) The apparatus as claimed in claim 3, wherein the base material is in the form of a net.